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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	752
Number of Logic Elements/Cells	6768
Total RAM Bits	516096
Number of I/O	140
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp4-5fg256c

Each RocketIO or RocketIO X core implements the following technology:

- Serializer and deserializer (SERDES)
- Monolithic clock synthesis and clock recovery (CDR)
- 10 Gigabit Attachment Unit Interface (XAUI) Fibre Channel (3.1875 Gb/s XAUI), Infiniband, PCI Express, Aurora, SXI-5 (SFI-5,/SPI-5), and OC-48 compatibility(1)
- 8/16/32-bit (RocketIO) or 8/16/32/64-bit (RocketIO X) selectable FPGA interface
- 8B/10B (RocketIO) or 8B/10B and 64B/66B (RocketIO X) encoder and decoder with bypassing option on each channel
- Channel bonding support (two to twenty channels)
  - Elastic buffers for inter-chip deskewing and channel-to-channel alignment
- Receiver clock recovery tolerance of up to 75 non-transitioning bits
- 50Ω (RocketIO X) or 50Ω /75Ω selectable (RocketIO) on-chip transmit and receive terminations
- Programmable comma detection and word alignment
- Rate matching via insertion/deletion characters
- Automatic lock-to-reference function
- Programmable pre-emphasis support
- Per-channel serial and parallel transmitter-to-receiver internal loopback modes
- Optional transmit and receive data inversion
- Cyclic Redundancy Check support (RocketIO only)

PowerPC 405 Processor Block

The PPC405 RISC CPU can execute instructions at a sustained rate of one instruction per cycle. On-chip instruction and data cache reduce design complexity and improve system throughput.

The PPC405 features include:

- PowerPC RISC CPU
  - Implements the PowerPC User Instruction Set Architecture (UISA) and extensions for embedded applications
  - Thirty-two 32-bit general purpose registers (GPRs)
  - Static branch prediction
  - Five-stage pipeline with single-cycle execution of most instructions, including loads/stores
  - Unaligned and aligned load/store support to cache, main memory, and on-chip memory
  - Hardware multiply/divide for faster integer arithmetic (4-cycle multiply, 35-cycle divide)
  - Enhanced string and multiple-word handling
  - Big/little endian operation support
- Storage Control
  - Separate instruction and data cache units, both two-way set-associative and non-blocking
  - Eight words (32 bytes) per cache line
  - 16 KB array Instruction Cache Unit (ICU), 16 KB array Data Cache Unit (DCU)
  - Operand forwarding during instruction cache line fill
  - Copy-back or write-through DCU strategy
  - Doubleword instruction fetch from cache improves branch latency
- Virtual mode memory management unit (MMU)
  - Translation of the 4 GB logical address space into physical addresses
  - Software control of page replacement strategy
  - Supports multiple simultaneous page sizes ranging from 1 KB to 16 MB
- OCM controllers provide dedicated interfaces between Block SelectRAM+ memory and processor block instruction and data paths for high-speed access
- PowerPC timer facilities
  - 64-bit time base
  - Programmable interval timer (PIT)
  - Fixed interval timer (FIT)
  - Watchdog timer (WDT)
- Debug Support
  - Internal debug mode
  - External debug mode
  - Debug Wait mode
  - Real Time Trace debug mode
  - Enhanced debug support with logical operators
  - Instruction trace and trace-back support
  - Forward or backward trace
- Two hardware interrupt levels support
- Advanced power management support

Input/Output Blocks (IOBs)

IOBs are programmable and can be categorized as follows:

- Input block with an optional single data rate (SDR) or double data rate (DDR) register
- Output block with an optional SDR or DDR register and an optional 3-state buffer to be driven directly or through an SDR or DDR register
- Bidirectional block (any combination of input and output configurations)

These registers are either edge-triggered D-type flip-flops or level-sensitive latches.

IOBs support the following single-ended I/O standards:

- LVTTL, LVCMOS (3.3V,(2) 2.5V, 1.8V, and 1.5V)
- PCI-X compatible (133 MHz and 66 MHz) at 3.3V(3)
- PCI compliant (66 MHz and 33 MHz) at 3.3V(3)
- GTL and GTLP

1. Refer to Table 4, Module 2 for detailed information about RocketIO and RocketIO X transceiver compatible protocols.
2. Refer to **XAPP659** for more information.
3. Refer to **XAPP653** for more information.

Output Swing and Emphasis

The output swing and emphasis levels are fully programmable. Each is controlled via attributes at configuration, and can be modified via the PMA attribute programming bus.

The programmable output swing control can adjust the differential peak-to-peak output level between 200 mV and 1600 mV.

With emphasis, the differential voltage swing is boosted to create a stronger rising or falling waveform. This method compensates for high frequency loss in the transmission media that would otherwise limit the magnitude of this waveform. Lossy transmission lines cause the dissipation of electrical energy. This emphasis technique extends the distance that signals can be driven down lossy line media and increases the signal-to-noise ratio at the receiver.

Emphasis can be described from two perspectives, additive to the smaller voltage (V_{SM}) (pre-emphasis) or subtractive from the larger voltage (V_{LG}) (de-emphasis). The resulting benefits in compensating for channel loss are identical. It is simply a relative way of specifying the effect at the transmitter.

The equations for calculating pre-emphasis as a percentage and dB are as follows:

$$\text{Pre-Emphasis}_{\%} = ((V_{LG}-V_{SM}) / V_{SM}) \times 100$$
$$\text{Pre-Emphasis}_{dB} = 20 \log(V_{LG}/V_{SM})$$

The equations for calculating de-emphasis as a percentage and dB are as follows:

$$\text{De-Emphasis}_{\%} = (V_{LG} - V_{SM}) / V_{LG}) \times 100$$
$$\text{De-Emphasis}_{dB} = 20 \log(V_{SM}/V_{LG})$$

The pre-emphasis amount can be programmed in discrete steps between 0% and 500%. The de-emphasis amount can be programmed in discrete steps between 0% and 83%.

Serializer

The serializer multiplies the reference frequency provided on REFCLK by 10, 16, 20, 32, or 40, depending on the operation mode. The multiplication of the clock is achieved by using an embedded PLL.

Data is converted from parallel to serial format and transmitted on the TXP and TXN differential outputs. The electrical connection of TXP and TXN can be interchanged through configuration. This option can be controlled by an input (TXPOLARITY) at the FPGA transmitter interface.

Deserializer

Synchronous serial data reception is facilitated by a clock and data recovery (CDR) circuit. This circuit uses a fully monolithic Phase Lock Loop (PLL), which does not require any external components. The CDR circuit extracts both phase and frequency from the incoming data stream.

The derived clock, RXRECCLK, is generated and locked to as long as it remains within the specified component range. This clock is presented to the FPGA fabric at $^1/_{10}$, $^1/_{16}$, $^1/_{20}$, $^1/_{32}$, or $^1/_{40}$ the incoming data rate depending on the operating mode.

A sufficient number of transitions must be present in the data stream for CDR to work properly. The CDR circuit is guaranteed to work with 8B/10B and 64B/66B encoding. Further, CDR requires approximately 5,000 transitions upon power-up to guarantee locking to the incoming data rate. Once lock is achieved, up to 75 missing transitions can be tolerated before lock to the incoming data stream is lost.

Another feature of CDR is its ability to accept an external precision reference clock, REFCLK, which either acts to clock incoming data or to assist in synchronizing the derived RXRECCLK.

For further clarity, the TXUSRCLK is used to clock data from the FPGA fabric to the TX FIFO. The FIFO depth accounts for the slight phase difference between these two clocks. If the clocks are locked in frequency, then the FIFO acts much like a pass-through buffer.

The receiver can be configured to reverse the RXP and RXN inputs. This can be useful in the event that printed circuit board traces have been reversed.

Receiver Lock Control

The CDR circuits will lock to the reference clock automatically if the data is not present. For proper operation, the frequency of the reference clock must be within ±100 ppm of the nominal frequency.

During normal operation, the receiver PLL automatically locks to incoming data (when present) or to the local reference clock (when data is not present). This is the default configuration for all primitives. This function can be overridden via the PMARXLOCKSEL port

When receive PLL lock is forced to the local reference, phase information from the incoming data stream is ignored. Data continues to be sampled, but synchronous to the local reference rather than relative to edges in the data stream.

Receive Equalization

In addition to transmit emphasis, the RocketIO X MGT provides a programmable active receive equalization feature to further compensate the effects of channel attenuation at high frequencies.

By adjusting RXFER, the right amount of equalization can be added to reverse the signal degradation caused by a printed circuit board, a backplane, or a line/switch card. RXFER can be set through software configuration or the PMA Attribute Bus.

Receiver Termination

On-chip termination is provided at the receiver, eliminating the need for external termination. The receiver termination supply (V_{TRX}) is the center tap of differential termination to

Functional Description: Processor Block

This section briefly describes the interfaces and components of the Processor Block. The subsequent section, Functional Description: Embedded PowerPC 405 Core beginning on page 20, offers a summary of major PPC405 core features. For an in-depth discussion on both the Processor Block and PPC405, see tthe **PowerPC Processor Reference Guide** and the **PowerPC 405 Processor Block Reference Guide** available on the Xilinx website at **http://www.xilinx.com**.

Processor Block Overview

Figure 14 shows the internal architecture of the Processor Block.

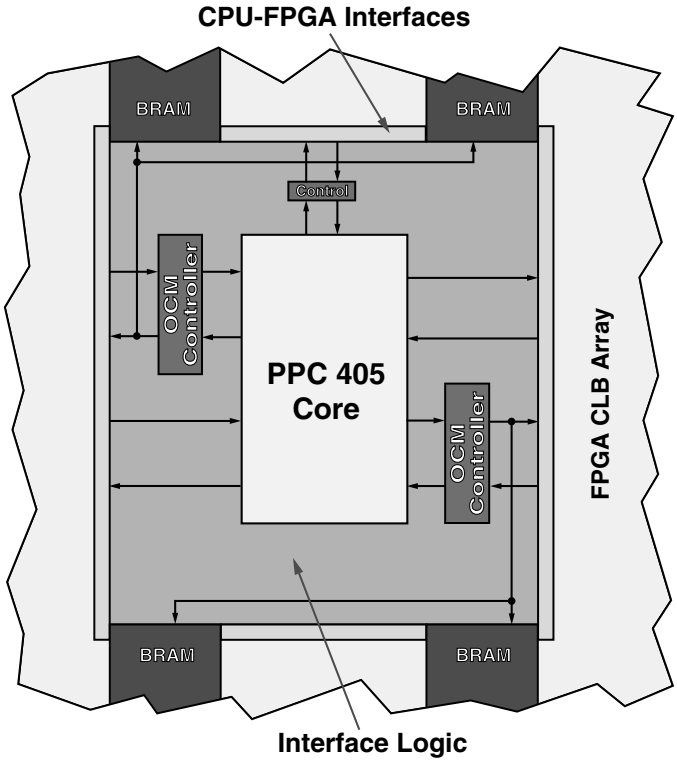

Figure 14: **Processor Block Architecture**

Within the Virtex-II Pro Processor Block, there are four components:

- Embedded IBM PowerPC 405-D5 RISC CPU core
- On-Chip Memory (OCM) controllers and interfaces
- Clock/control interface logic
- CPU-FPGA Interfaces

Embedded PowerPC 405 RISC Core

The PowerPC 405D5 core is a 0.13 µm implementation of the IBM PowerPC 405D4 core. The advanced process technology enables the embedded PowerPC 405 (PPC405) core to operate at 300+ MHz while maintaining low power consumption. Specially designed interface logic integrates the core with the surrounding CLBs, block RAMs, and general routing resources. Up to four Processor Blocks can be available in a single Virtex-II Pro device.

The embedded PPC405 core implements the PowerPC User Instruction Set Architecture (UISA), user-level registers, programming model, data types, and addressing modes for 32-bit fixed-point operations. 64-bit operations, auxiliary processor operations, and floating-point operations are trapped and can be emulated in software.

Most of the PPC405 core features are compatible with the specifications for the PowerPC Virtual Environment Architecture (VEA) and Operating Environment Architecture (OEA). They also provide a number of optimizations and extensions to the lower layers of the PowerPC Architecture. The full architecture of the PPC405 is defined by the PowerPC Embedded Environment and PowerPC UISA documentation, available from IBM.

On-Chip Memory (OCM) Controllers

Introduction

The OCM controllers serve as dedicated interfaces between the block RAMs in the FPGA fabric (see 18 Kb Block SelectRAM+ Resources, page 44) and OCM signals available on the embedded PPC405 core. The OCM signals on the PPC405 core are designed to provide very quick access to a fixed amount of instruction and data memory space. The OCM controller provides an interface to both the 64-bit Instruction-Side Block RAM (ISBRAM) and the 32-bit Data-Side Block RAM (DSBRAM). The designer can choose to implement:

- ISBRAM only
- DSBRAM only
- Both ISBRAM and DSBRAM
- No ISBRAM and no DSBRAM

One of OCM's primary advantages is that it guarantees a fixed latency of execution for a higher level of determinism. Additionally, it reduces cache pollution and thrashing, since the cache remains available for caching code from other memory resources.

Typical applications for DSOCM include scratch-pad memory, as well as use of the dual-port feature of block RAM to enable bidirectional data transfer between processor and FPGA. Typical applications for ISOCM include storage of interrupt service routines.

Functional Features

Common Features

- Separate Instruction and Data memory interface between processor core and BRAMs in FPGA
- Dedicated interface to Device Control Register (DCR) bus for ISOCM and DSOCM

Output Delay Measurements

Output delays are measured using a Tektronix P6245 TDS500/600 probe (< 1 pF) across approximately 4" of FR4 microstrip trace. Standard termination was used for all testing. (See ***Virtex-II Pro Platform FPGA User Guide*** for details.) The propagation delay of the 4" trace is characterized separately and subtracted from the final measurement, and is therefore not included in the generalized test setup shown in Figure 6.

Measurements and test conditions are reflected in the IBIS models except where the IBIS format precludes it. (IBIS models can be found on the web at **http://support.xilinx.com/support/sw_ibis.htm**.) Parameters V_{REF}, R_{REF}, C_{REF}, and V_{MEAS} fully describe the test conditions for each I/O standard. The most accurate prediction of propagation delay in any given application can be obtained through IBIS simulation, using the following method:

1. Simulate the output driver of choice into the generalized test setup, using values from Table 40.
2. Record the time to V_{MEAS}.
3. Simulate the output driver of choice into the actual PCB trace and load, using the appropriate IBIS model or capacitance value to represent the load.
4. Record the time to V_{MEAS}.
5. Compare the results of steps 2 and 4. The increase or decrease in delay should be added to or subtracted from the I/O Output Standard Adjustment value (Table 38) to yield the actual worst-case propagation delay (clock-to-input) of the PCB trace.

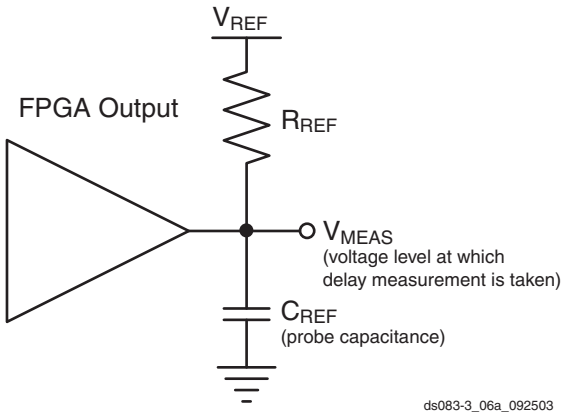

Figure 6: **Generalized Test Setup**

Table 40: **Output Delay Measurement Methodology**

Description	IOSTANDARD Attribute	R_{REF} (Ω)	C_{REF} (1) (pF)	V_{MEAS} (V)	V_{REF} (V)
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL (all)	1M	0	1.65	0
LVCMOS (Low-Voltage CMOS), 3.3V	LVCMOS33	1M	0	1.65	0
LVCMOS, 2.5V	LVCMOS25	1M	0	1.25	0
LVCMOS, 1.8V	LVCMOS18	1M	0	0.9	0
LVCMOS, 1.5V	LVCMOS15	1M	0	0.75	0
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3 (rising edge)	25	10 (2)	0.94	0
	PCI33_3 (falling edge)	25	10 (2)	2.03	3.3
PCI, 66 MHz, 3.3V	PCI66_3 (rising edge)	25	10 (2)	0.94	0
	PCI66_3 (falling edge)	25	10 (2)	2.03	3.3
PCI-X, 133 MHz, 3.3V	PCIX (rising edge)	25	10 (3)	0.94	0
	PCIX (falling edge	25	10 (3)	2.03	3.3
GTL (Gunning Transceiver Logic)	GTL	25	0	0.8	1.2
GTL Plus	GTLP	25	0	1.0	1.5
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	50	0	V_{REF}	0.75
HSTL, Class II	HSTL_II	25	0	V_{REF}	0.75
HSTL, Class III	HSTL_III	50	0	0.9	1.5
HSTL, Class IV	HSTL_IV	25	0	0.9	1.5
HSTL, Class I, 1.8V	HSTL_I_18	50	0	V_{REF}	0.9
HSTL, Class II, 1.8V	HSTL_II_18	25	0	V_{REF}	0.9
HSTL, Class III, 1.8V	HSTL_III_18	50	0	1.1	1.8
HSTL, Class IV, 1.8V	HSTL_IV_18	25	0	1.1	1.8

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VCCAUX	L1			
N/A	VCCAUX	B21			
N/A	VCCAUX	B2			
N/A	VCCAUX	AB11			
N/A	VCCAUX	AA21			
N/A	VCCAUX	AA2			
N/A	VCCAUX	A12			
N/A	GND	Y3			
N/A	GND	Y20			
N/A	GND	W4			
N/A	GND	W19			
N/A	GND	V5			
N/A	GND	V18			
N/A	GND	P9			
N/A	GND	P14			
N/A	GND	P13			
N/A	GND	P12			
N/A	GND	P11			
N/A	GND	P10			
N/A	GND	N9			
N/A	GND	N14			
N/A	GND	N13			
N/A	GND	N12			
N/A	GND	N11			
N/A	GND	N10			
N/A	GND	M9			
N/A	GND	M14			
N/A	GND	M13			
N/A	GND	M12			
N/A	GND	M11			
N/A	GND	M10			
N/A	GND	M1			
N/A	GND	L9			
N/A	GND	L22			
N/A	GND	L14			
N/A	GND	L13			
N/A	GND	L12			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
5	IO_L46N_5	W11			
5	IO_L46P_5	W10			
5	IO_L45N_5/VREF_5	AD9			
5	IO_L45P_5	AC9			
5	IO_L43N_5	AB9			
5	IO_L43P_5	AA9			
5	IO_L39N_5	Y9			
5	IO_L39P_5	W9			
5	IO_L37N_5	AF8			
5	IO_L37P_5	AE8			
5	IO_L09N_5/VREF_5	AB8			
5	IO_L09P_5	AA8			
5	IO_L07N_5/VREF_5	Y8			
5	IO_L07P_5	W8			
5	IO_L06N_5/VRP_5	AD7			
5	IO_L06P_5/VRN_5	AC7			
5	IO_L05_5/No_Pair	AB7			
5	IO_L03N_5/D4	AA7			
5	IO_L03P_5/D5	Y7			
5	IO_L02N_5/D6	AC6			
5	IO_L02P_5/D7	AB6			
5	IO_L01N_5/RDWR_B	AC5			
5	IO_L01P_5/CS_B	AB5			
6	IO_L01P_6/VRN_6	AE1			
6	IO_L01N_6/VRP_6	AD1			
6	IO_L02P_6	AD2			
6	IO_L02N_6	AC3			
6	IO_L03P_6	AC2			
6	IO_L03N_6/VREF_6	AC1			
6	IO_L05P_6	AB4			
6	IO_L05N_6	AA5			
6	IO_L06P_6	AB2			
6	IO_L06N_6	AB1			
6	IO_L23P_6	AA6	NC		

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	GND	H4			
N/A	GND	H23			
N/A	GND	K6			
N/A	GND	K21			
N/A	GND	L11			
N/A	GND	L12			
N/A	GND	L13			
N/A	GND	L14			
N/A	GND	L15			
N/A	GND	L16			
N/A	GND	M3			
N/A	GND	M11			
N/A	GND	M12			
N/A	GND	M13			
N/A	GND	M14			
N/A	GND	M15			
N/A	GND	M16			
N/A	GND	M24			
N/A	GND	N11			
N/A	GND	N12			
N/A	GND	N13			
N/A	GND	N14			
N/A	GND	N15			
N/A	GND	N16			
N/A	GND	P11			
N/A	GND	P12			
N/A	GND	P13			
N/A	GND	P14			
N/A	GND	P15			
N/A	GND	P16			
N/A	GND	R3			
N/A	GND	R11			
N/A	GND	R12			
N/A	GND	R13			
N/A	GND	R14			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
3	IO_L48N_3	W1	NC		
3	IO_L48P_3	W2	NC		
3	IO_L47N_3	W3	NC		
3	IO_L47P_3	W4	NC		
3	IO_L46N_3	W5	NC		
3	IO_L46P_3	W6	NC		
3	IO_L45N_3/VREF_3	Y1	NC		
3	IO_L45P_3	AA1	NC		
3	IO_L44N_3	Y3	NC		
3	IO_L44P_3	Y4	NC		
3	IO_L43N_3	Y5	NC		
3	IO_L43P_3	Y6	NC		
3	IO_L42N_3	AA2	NC	NC	NC
3	IO_L42P_3	AA3	NC	NC	NC
3	IO_L41N_3	AA4	NC	NC	NC
3	IO_L41P_3	AA5	NC	NC	NC
3	IO_L39N_3/VREF_3	AB1	NC	NC	NC
3	IO_L39P_3	AB2	NC	NC	NC
3	IO_L06N_3	AB3			
3	IO_L06P_3	AB4			
3	IO_L05N_3	AC1			
3	IO_L05P_3	AC2			
3	IO_L04N_3	AD1			
3	IO_L04P_3	AD2			
3	IO_L03N_3/VREF_3	AE1			
3	IO_L03P_3	AF2			
3	IO_L02N_3	AC3			
3	IO_L02P_3	AD4			
3	IO_L01N_3/VRP_3	AE3			
3	IO_L01P_3/VRN_3	AF3			
4	IO_L01N_4/BUSY/DOUT(1)	AC6			
4	IO_L01P_4/INIT_B	AD6			
4	IO_L02N_4/D0/DIN(1)	AB7			
4	IO_L02P_4/D1	AC7			
4	IO_L03N_4/D2	AA7			
4	IO_L03P_4/D3	AA8			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VCCINT	U16			
N/A	VCCINT	U18			
N/A	VCCINT	V10			
N/A	VCCINT	V17			
N/A	VCCINT	V18			
N/A	VCCINT	W19			
N/A	VCCAUX	B2			
N/A	VCCAUX	N1			
N/A	VCCAUX	P1			
N/A	VCCAUX	A13			
N/A	VCCAUX	A14			
N/A	VCCAUX	AE2			
N/A	VCCAUX	B25			
N/A	VCCAUX	N26			
N/A	VCCAUX	P26			
N/A	VCCAUX	AE25			
N/A	VCCAUX	AF13			
N/A	VCCAUX	AF14			
N/A	GND	C3			
N/A	GND	D4			
N/A	GND	E5			
N/A	GND	F6			
N/A	GND	G7			
N/A	GND	Y7			
N/A	GND	AA6			
N/A	GND	AB5			
N/A	GND	AC4			
N/A	GND	AD3			
N/A	GND	C24			
N/A	GND	D23			
N/A	GND	E22			
N/A	GND	F21			
N/A	GND	G20			
N/A	GND	K10			
N/A	GND	K12			
N/A	GND	K13			
N/A	GND	K14			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	GND	K15			
N/A	GND	K17			
N/A	GND	L11			
N/A	GND	L12			
N/A	GND	L13			
N/A	GND	L14			
N/A	GND	L15			
N/A	GND	L16			
N/A	GND	M10			
N/A	GND	M11			
N/A	GND	M12			
N/A	GND	M13			
N/A	GND	M14			
N/A	GND	M15			
N/A	GND	M16			
N/A	GND	M17			
N/A	GND	N10			
N/A	GND	N11			
N/A	GND	N12			
N/A	GND	N13			
N/A	GND	N14			
N/A	GND	N15			
N/A	GND	N16			
N/A	GND	N17			
N/A	GND	P10			
N/A	GND	P11			
N/A	GND	P12			
N/A	GND	P13			
N/A	GND	P14			
N/A	GND	P15			
N/A	GND	P16			
N/A	GND	P17			
N/A	GND	R10			
N/A	GND	R11			
N/A	GND	R12			
N/A	GND	R13			
N/A	GND	R14			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L53_0/No_Pair		A21	NC		
0	IO_L54N_0		H18	NC		
0	IO_L54P_0		G18	NC		
0	IO_L56N_0		C21	NC		
0	IO_L56P_0		C20	NC		
0	IO_L57N_0		J17	NC		
0	IO_L57P_0/VREF_0		H17	NC		
0	IO_L67N_0		E17			
0	IO_L67P_0		D17			
0	IO_L68N_0		D18			
0	IO_L68P_0		C18			
0	IO_L69N_0		J16			
0	IO_L69P_0/VREF_0		H16			
0	IO_L73N_0		E16			
0	IO_L73P_0		D16			
0	IO_L74N_0/GCLK7P		C16			
0	IO_L74P_0/GCLK6S		B16			
0	IO_L75N_0/GCLK5P	BREFCLKN	G16			
0	IO_L75P_0/GCLK4S	BREFCLKP	F16			
1	IO_L75N_1/GCLK3P		F15			
1	IO_L75P_1/GCLK2S		G15			
1	IO_L74N_1/GCLK1P		B15			
1	IO_L74P_1/GCLK0S		C15			
1	IO_L73N_1		D15			
1	IO_L73P_1		E15			
1	IO_L69N_1/VREF_1		H15			
1	IO_L69P_1		J15			
1	IO_L68N_1		C13			
1	IO_L68P_1		D13			
1	IO_L67N_1		D14			
1	IO_L67P_1		E14			
1	IO_L57N_1/VREF_1		H14	NC		
1	IO_L57P_1		J14	NC		
1	IO_L56N_1		C11	NC		
1	IO_L56P_1		C10	NC		

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
7	IO_L36N_7		F27	NC		
7	IO_L35P_7		K24	NC		
7	IO_L35N_7		K23	NC		
7	IO_L34P_7		E30	NC		
7	IO_L34N_7/VREF_7		E29	NC		
7	IO_L33P_7		E28	NC		
7	IO_L33N_7		E27	NC		
7	IO_L32P_7		H26	NC		
7	IO_L32N_7		H25	NC		
7	IO_L31P_7		D30	NC		
7	IO_L31N_7		D29	NC		
7	IO_L06P_7		D28			
7	IO_L06N_7		C27			
7	IO_L05P_7		J24			
7	IO_L05N_7		J23			
7	IO_L04P_7		C30			
7	IO_L04N_7/VREF_7		C29			
7	IO_L03P_7		D26			
7	IO_L03N_7		C26			
7	IO_L02P_7		G26			
7	IO_L02N_7		G25			
7	IO_L01P_7/VRN_7		B28			
7	IO_L01N_7/VRP_7		A28			
0	VCCO_0		K21			
0	VCCO_0		K20			
0	VCCO_0		K19			
0	VCCO_0		K18			
0	VCCO_0		K17			
0	VCCO_0		K16			
0	VCCO_0		J21			
0	VCCO_0		J20			
0	VCCO_0		J19			
0	VCCO_0		J18			
1	VCCO_1		K15			
1	VCCO_1		K14			

FF1152 Flip-Chip Fine-Pitch BGA Package

As shown in Table 10, XC2VP20, XC2VP30, XC2VP40, and XC2VP50 Virtex-II Pro devices are available in the FF1152 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for the differences shown in the No Connect column. Following this table are the FF1152 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
0	IO_L01N_0/VRP_0	E29				
0	IO_L01P_0/VRN_0	E28				
0	IO_L02N_0	H26				
0	IO_L02P_0	G26				
0	IO_L03N_0	H25				
0	IO_L03P_0/VREF_0	G25				
0	IO_L05_0/No_Pair	J25				
0	IO_L06N_0	K24				
0	IO_L06P_0	J24				
0	IO_L07N_0	F26				
0	IO_L07P_0	E26				
0	IO_L08N_0	D30				
0	IO_L08P_0	D29				
0	IO_L09N_0	K23				
0	IO_L09P_0/VREF_0	J23				
0	IO_L19N_0	F24	NC	NC		
0	IO_L19P_0	E24	NC	NC		
0	IO_L20N_0	D28	NC	NC		
0	IO_L20P_0	C28	NC	NC		
0	IO_L21N_0	H24	NC	NC		
0	IO_L21P_0	G24	NC	NC		
0	IO_L25N_0	G23	NC	NC		
0	IO_L25P_0	F23	NC	NC		
0	IO_L26N_0	E27	NC	NC		
0	IO_L26P_0	D27	NC	NC		
0	IO_L27N_0	K22	NC	NC		
0	IO_L27P_0/VREF_0	J22	NC	NC		
0	IO_L37N_0	H22				
0	IO_L37P_0	G22				
0	IO_L38N_0	D26				
0	IO_L38P_0	C26				
0	IO_L39N_0	K21				
0	IO_L39P_0	J21				
0	IO_L43N_0	F22				

FF1148 Flip-Chip Fine-Pitch BGA Package

As shown in Table 11, XC2VP40 and XC2VP50 Virtex-II Pro devices are available in the FF1148 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for the differences shown in the No Connect column. Following this table are the FF1148 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
0	IO_L01N_0/VRP_0	E25		
0	IO_L01P_0/VRN_0	F25		
0	IO_L02N_0	J24		
0	IO_L02P_0	K24		
0	IO_L03N_0	C25		
0	IO_L03P_0/VREF_0	D25		
0	IO_L05_0/No_Pair	G25		
0	IO_L06N_0	A25		
0	IO_L06P_0	B25		
0	IO_L07N_0	G24		
0	IO_L07P_0	G23		
0	IO_L08N_0	H23		
0	IO_L08P_0	H22		
0	IO_L09N_0	E24		
0	IO_L09P_0/VREF_0	F24		
0	IO_L19N_0	C24		
0	IO_L19P_0	C23		
0	IO_L20N_0	J23		
0	IO_L20P_0	K23		
0	IO_L21N_0	A24		
0	IO_L21P_0	B24		
0	IO_L25N_0	E23		
0	IO_L25P_0	F23		
0	IO_L26N_0	K22		
0	IO_L26P_0	L22		
0	IO_L27N_0	D23		
0	IO_L27P_0/VREF_0	D22		
0	IO_L37N_0	A23		
0	IO_L37P_0	B23		
0	IO_L38N_0	J21		
0	IO_L38P_0	J20		
0	IO_L39N_0	F22		
0	IO_L39P_0	G22		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
4	IO_L47N_4	AE15		
4	IO_L47P_4	AD15		
4	IO_L48N_4	AM14		
4	IO_L48P_4	AL14		
4	IO_L49N_4	AP14		
4	IO_L49P_4	AN14		
4	IO_L50_4/No_Pair	AH15		
4	IO_L53_4/No_Pair	AG16		
4	IO_L54N_4	AK15		
4	IO_L54P_4	AJ15		
4	IO_L55N_4	AM15		
4	IO_L55P_4	AL16		
4	IO_L56N_4	AE16		
4	IO_L56P_4	AD16		
4	IO_L57N_4	AP15		
4	IO_L57P_4/VREF_4	AN15		
4	IO_L66N_4	AJ16	NC	
4	IO_L66P_4/VREF_4	AH16	NC	
4	IO_L67N_4	AN16		
4	IO_L67P_4	AM16		
4	IO_L68N_4	AG17		
4	IO_L68P_4	AF17		
4	IO_L69N_4	AJ17		
4	IO_L69P_4/VREF_4	AH17		
4	IO_L73N_4	AL17		
4	IO_L73P_4	AK17		
4	IO_L74N_4/GCLK3S	AE17		
4	IO_L74P_4/GCLK2P	AD17		
4	IO_L75N_4/GCLK1S	AN17		
4	IO_L75P_4/GCLK0P	AM17		
5	IO_L75N_5/GCLK7S	AM18		
5	IO_L75P_5/GCLK6P	AN18		
5	IO_L74N_5/GCLK5S	AD18		
5	IO_L74P_5/GCLK4P	AE18		
5	IO_L73N_5	AK18		
5	IO_L73P_5	AL18		
5	IO_L69N_5/VREF_5	AH18		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	RXPPAD17		BB15		
N/A	GNDA17		AY16		
N/A	TXPPAD17		BB16		
N/A	TXNPAD17		BB17		
N/A	VTTXPAD17		BA17		
N/A	AVCCAUXTX17		BA16		
N/A	AVCCAUXRX18		BA18		
N/A	VTRXPAD18		BA19		
N/A	RXNPAD18		BB18		
N/A	RXPPAD18		BB19		
N/A	GNDA18		AY21		
N/A	TXPPAD18		BB20		
N/A	TXNPAD18		BB21		
N/A	VTTXPAD18		BA21		
N/A	AVCCAUXTX18		BA20		
N/A	AVCCAUXRX19		BA22		
N/A	VTRXPAD19		BA23		
N/A	RXNPAD19		BB22		
N/A	RXPPAD19		BB23		
N/A	GNDA19		AY22		
N/A	TXPPAD19		BB24		
N/A	TXNPAD19		BB25		
N/A	VTTXPAD19		BA25		
N/A	AVCCAUXTX19		BA24		
N/A	AVCCAUXRX20		BA26		
N/A	VTRXPAD20		BA27		
N/A	RXNPAD20		BB26		
N/A	RXPPAD20		BB27		
N/A	GNDA20		AY27		
N/A	TXPPAD20		BB28		
N/A	TXNPAD20		BB29		
N/A	VTTXPAD20		BA29		
N/A	AVCCAUXTX20		BA28		
N/A	AVCCAUXRX21		BA30		
N/A	VTRXPAD21		BA31		
N/A	RXNPAD21		BB30		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
0	IO_L67P_0	J22	
0	IO_L68N_0	K23	
0	IO_L68P_0	L23	
0	IO_L69N_0	F22	
0	IO_L69P_0/VREF_0	G22	
0	IO_L73N_0	D22	
0	IO_L73P_0	E22	
0	IO_L74N_0/GCLK7P	K22	
0	IO_L74P_0/GCLK6S	L22	
0	IO_L75N_0/GCLK5P	B22	
0	IO_L75P_0/GCLK4S	C22	
1	IO_L75N_1/GCLK3P	C21	
1	IO_L75P_1/GCLK2S	B21	
1	IO_L74N_1/GCLK1P	L21	
1	IO_L74P_1/GCLK0S	K21	
1	IO_L73N_1	E21	
1	IO_L73P_1	D21	
1	IO_L69N_1/VREF_1	G21	
1	IO_L69P_1	F21	
1	IO_L68N_1	L20	
1	IO_L68P_1	K20	
1	IO_L67N_1	J21	
1	IO_L67P_1	H21	
1	IO_L66N_1/VREF_1	C20	
1	IO_L66P_1	B20	
1	IO_L65N_1	M20	
1	IO_L65P_1	M21	
1	IO_L64N_1	G20	
1	IO_L64P_1	F20	
1	IO_L60N_1	B19	
1	IO_L60P_1	A19	
1	IO_L59N_1	K19	
1	IO_L59P_1	J19	
1	IO_L58N_1	D19	
1	IO_L58P_1	D20	
1	IO_L57N_1/VREF_1	F19	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	IO_L75N_2	C5	
2	IO_L75P_2	B5	
2	IO_L76N_2/VREF_2	D7	
2	IO_L76P_2	C6	
2	IO_L77N_2	H8	
2	IO_L77P_2	H9	
2	IO_L78N_2	C3	
2	IO_L78P_2	C4	
2	IO_L79N_2	D1	
2	IO_L79P_2	D2	
2	IO_L80N_2	J8	
2	IO_L80P_2	K9	
2	IO_L81N_2	E6	
2	IO_L81P_2	D5	
2	IO_L82N_2/VREF_2	E4	
2	IO_L82P_2	D4	
2	IO_L83N_2	L8	
2	IO_L83P_2	L9	
2	IO_L84N_2	E3	
2	IO_L84P_2	D3	
2	IO_L61N_2	F8	
2	IO_L61P_2	E8	
2	IO_L62N_2	M8	
2	IO_L62P_2	M9	
2	IO_L63N_2	F7	
2	IO_L63P_2	E7	
2	IO_L64N_2/VREF_2	F3	
2	IO_L64P_2	E2	
2	IO_L65N_2	N12	
2	IO_L65P_2	P12	
2	IO_L66N_2	F1	
2	IO_L66P_2	F2	
2	IO_L67N_2	G7	
2	IO_L67P_2	G8	
2	IO_L68N_2	N10	
2	IO_L68P_2	N11	
2	IO_L69N_2	G6	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L02P_6	BA34	
6	IO_L02N_6	AY34	
6	IO_L03P_6	BB37	
6	IO_L03N_6/VREF_6	BA37	
6	IO_L04P_6	BB36	
6	IO_L04N_6	BA36	
6	IO_L05P_6	AW34	
6	IO_L05N_6	AW35	
6	IO_L06P_6	BB35	
6	IO_L06N_6	BA35	
6	IO_L73P_6	BA38	
6	IO_L73N_6	AY38	
6	IO_L74P_6	AU34	
6	IO_L74N_6	AT34	
6	IO_L75P_6	AY39	
6	IO_L75N_6/VREF_6	AY40	
6	IO_L76P_6	AY37	
6	IO_L76N_6	AW36	
6	IO_L77P_6	AR34	
6	IO_L77N_6	AR35	
6	IO_L78P_6	AY35	
6	IO_L78N_6	AY36	
6	IO_L79P_6	AW41	
6	IO_L79N_6	AW42	
6	IO_L80P_6	AP35	
6	IO_L80N_6	AN34	
6	IO_L81P_6	AW40	
6	IO_L81N_6/VREF_6	AV40	
6	IO_L82P_6	AW39	
6	IO_L82N_6	AV39	
6	IO_L83P_6	AM34	
6	IO_L83N_6	AM35	
6	IO_L84P_6	AW38	
6	IO_L84N_6	AV37	
6	IO_L61P_6	AV41	
6	IO_L61N_6	AU40	
6	IO_L62P_6	AL34	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	BB34	
N/A	GND	AV34	
N/A	GND	AP34	
N/A	GND	AK34	
N/A	GND	AF34	
N/A	GND	AC34	
N/A	GND	Y34	
N/A	GND	U34	
N/A	GND	N34	
N/A	GND	J34	
N/A	GND	E34	
N/A	GND	A34	
N/A	GND	AD31	
N/A	GND	W31	
N/A	GND	BB30	
N/A	GND	AV30	
N/A	GND	AP30	
N/A	GND	J30	
N/A	GND	E30	
N/A	GND	A30	
N/A	GND	BB26	
N/A	GND	AV26	
N/A	GND	AP26	
N/A	GND	AE26	
N/A	GND	AD26	
N/A	GND	AC26	
N/A	GND	AB26	
N/A	GND	AA26	
N/A	GND	Y26	
N/A	GND	W26	
N/A	GND	V26	
N/A	GND	J26	
N/A	GND	E26	
N/A	GND	A26	
N/A	GND	AF25	
N/A	GND	AE25	
N/A	GND	AD25	